

Ten Output Zero Delay Buffer

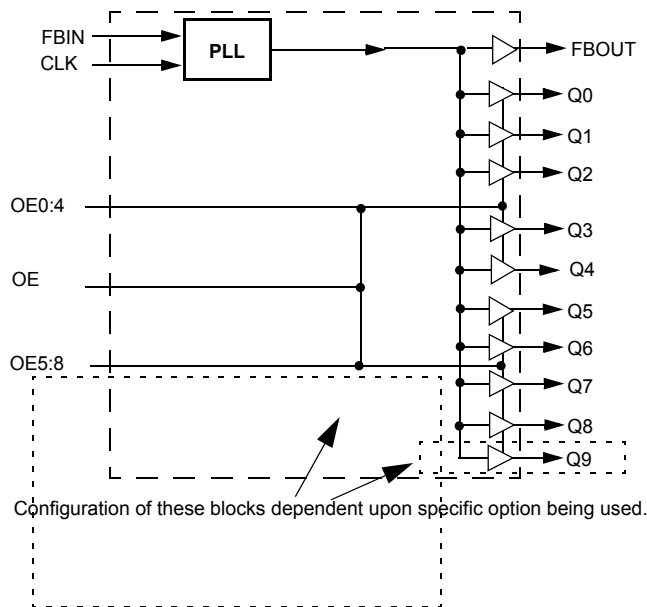
Features

- Well-Suited to both 100 and 133 MHz Designs
- 10 or 11 LVCMOS/LVTTL Outputs
- 3.3V Power Supply
- Available in 24-Pin TSSOP Package

Key Specifications

- Operating Voltage: $3.3V \pm 10\%$
- Operating Range: $25 \text{ MHz} < f_{OUT} < 140 \text{ MHz}$
- Cycle-to-Cycle Jitter less than 150 ps
- Output to Output Skew less than 100 ps
- Phase Error Jitter less than 125 ps
- Static Phase Error: less than 150 ps

Logic Block Diagram



Pinouts

Figure 1. 24-Pin TSSOP - W232-09

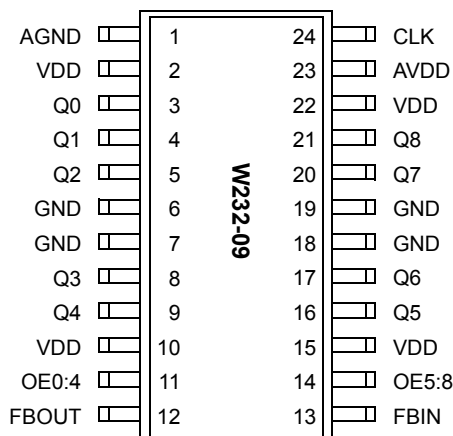
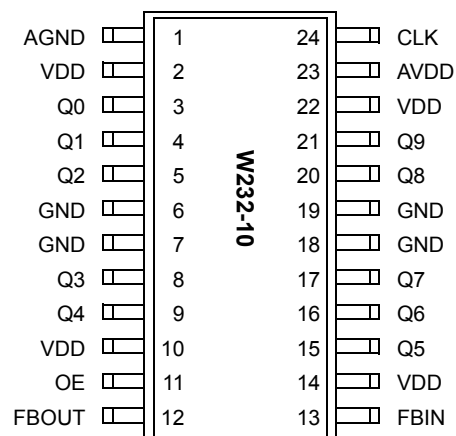


Figure 2. 24-Pin TSSOP - W232-10



Pin Definitions

Pin Name	Pin No. (-09)	Pin No. (-10)	Pin Type	Pin Description
CLK	24	24	I	Reference Input: Output signals Q0:9 are synchronized to this signal.
FBIN	13	13	I	Feedback Input: This input must be fed by one of the outputs (typically FBOUT) to ensure proper functionality. If the trace between FBIN and FBOUT is equal in length to the traces between the outputs and the signal destinations, then the signals received at the destinations are synchronized to the CLK signal input.
Q0:8	3, 4, 5, 8, 9, 16, 17, 20, 21	3, 4, 5, 8, 9, 15, 16, 17, 20, 21	O	Outputs: The frequency and phase of the signals provided by these pins are equal to the reference signal if properly laid out.
FBOUT	12	12	O	Feedback Output: Typically this is connected directly to the FBIN input with a trace equal in length to the traces between outputs Q0:9 and the destination points of these output signals.
AVDD	23	23	P	Analog Power Connection: Connect to 3.3V. Use ferrite beads to help reduce noise for optimal jitter performance.
AGND	1	1	G	Analog Ground Connection: Connect to common system ground plane.
VDD	2, 10, 15, 22	2, 10, 14 22	P	Power Connections: Connect to 3.3V. Use ferrite beads to help reduce noise for optimal jitter performance.
GND	6, 7, 18, 19	6, 7, 18, 19	G	Ground Connections: Connect to common system ground plane.
OE0:4	11	–	I	Output Enable Input: Tie to V_{DD} (HIGH, 1) for normal operation. When brought to GND (LOW, 0) outputs Q0:4 are disabled to a LOW state.
OE	–	11	I	Output Enable Input: Tie to V_{DD} (HIGH, 1) for normal operation. When brought to GND (LOW, 0) outputs Q0:9 are disabled to a LOW state.
OE5:8	14	–	I	Output Enable Input: Tie to V_{DD} (HIGH, 1) for normal operation. When brought to GND (LOW, 0) outputs Q5:8 are disabled to a LOW state.

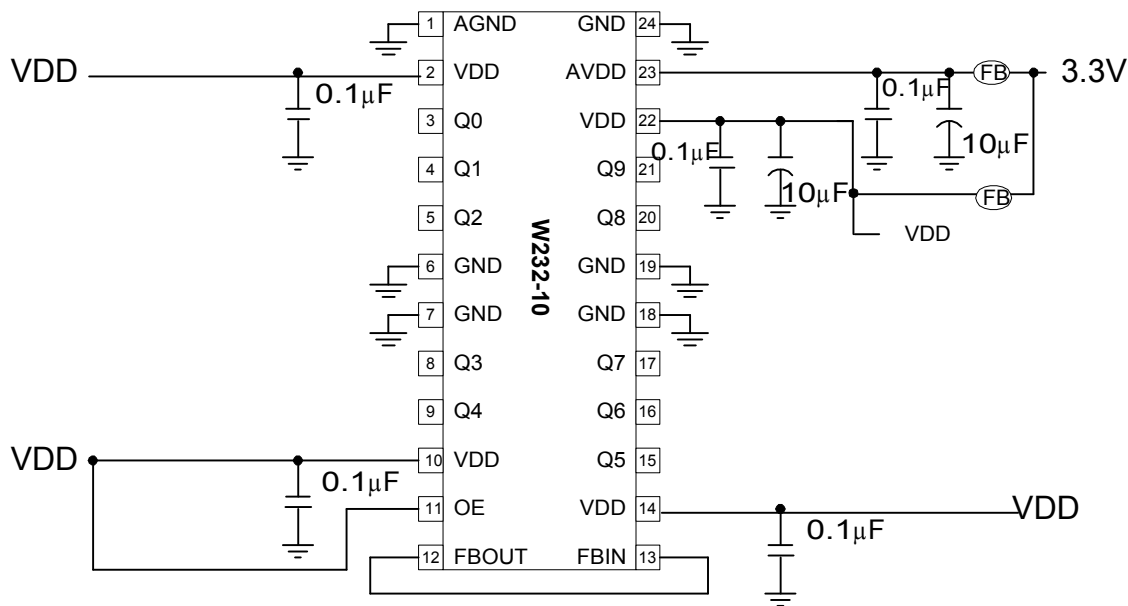
Overview

The W232 is a PLL-based clock driver designed for use in systems requiring a large number of synchronous timing signals. The clock driver has output frequencies of up to 140 MHz and output-to-output skews of less than 100 ps. The W232 provides minimum cycle-to-cycle and long-term jitter, which is of significant importance to meet the tight input-to-input skew budget in DIMM applications.

The W232 was specifically designed to accept SSFTG signals currently being used in motherboard designs to reduce EMI. Zero delay buffers which are not designed to pass this feature through may cause skewing failures.

Output enable pins allow shutdown of output when they are not being used. This reduces EMI and power consumption.

Figure 3. Schematic



Spread Aware

Many systems being designed now use a technology called Spread Spectrum Frequency Timing Generation (SSFTG). Cypress has been one of the pioneers of SSFTG development, and designed this product so as not to filter off the Spread Spectrum (SS) feature of the Reference input, assuming it exists. When a zero delay buffer is not designed to pass the SS feature through, the result is a significant amount of tracking skew which may cause problems in systems requiring synchronization.

For more details on SS timing technology, see the Cypress application note titled, "EMI Suppression Techniques with Spread Spectrum Frequency Timing Generator (SSFTG) ICs" - AN1278.

How to Implement Zero Delay

Typically, Zero Delay Buffers (ZDBs) are used because a designer wants to provide multiple copies of a clock signal in phase with each other. The whole concept behind ZDBs is that the signals at the destination chips are all going HIGH at the same time as the input to the ZDB. To achieve this, layout must compensate for trace length between the ZDB and the target devices. The method of compensation is as follows.

External feedback is the trait that allows this compensation. Since the PLL on the ZDB causes the feedback signal to be in phase with the reference signal, when laying out the board, match the trace lengths between the output being used for feedback and the FBIN input to the PLL.

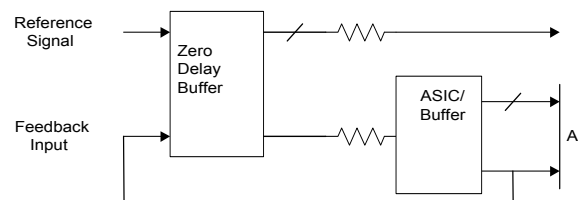
If it is desirable to either add a little delay, or slightly precede the input signal, this may also be affected by either making the trace to the FBIN pin a little shorter or a little longer than the traces to the devices being clocked.

Inserting Other Devices in Feedback Path

Another nice feature available due to the external feedback is the ability to synchronize signals up to the signal coming from some other device. This implementation can be applied to any device (ASIC, multiple output clock buffer/driver, and so on) which is put into the feedback path.

As shown in Figure 4, if the traces between the ASIC/buffer and the destination of the clock signal(s) (A) are equal in length to the trace between the buffer and the FBIN pin, the signals at the destination(s) device are driven HIGH at the same time the Reference clock provided to the ZDB goes HIGH. Synchronizing the other outputs of the ZDB to the outputs from the ASIC/Buffer is, however, more complex as any propagation delay in the ASIC/Buffer must be accounted for.

Figure 4. 6 Output Buffer in the Feedback Path



Absolute Maximum Ratings^[1]

Stresses greater than those listed in this table may cause permanent damage to the device. These represent a stress rating only. Operation of the device at these or any other conditions above those specified in the operating sections of this specification is not implied. Maximum conditions for extended periods may affect reliability.

Parameter	Description	Rating	Unit
V_{DD}, V_{IN}	Voltage on any Pin with Respect to GND	-0.5 to +7.0	V
T_{STG}	Storage Temperature	-65 to +150	°C
T_A	Operating Temperature	0 to +70	°C
T_B	Ambient Temperature under Bias	-55 to +125	°C
P_D	Power Dissipation	0.5	W

DC Electrical Characteristics: $T_A = 0^{\circ}\text{C}$ to 70°C , $V_{DD} = 3.3\text{V} \pm 10\%$

Parameter	Description	Test Condition	Min	Typ	Max	Unit
I_{DD}	Supply Current	Unloaded, 100 MHz			200	mA
V_{IL}	Input Low Voltage				0.8	V
V_{IH}	Input High Voltage		2.0			V
V_{OL}	Output Low Voltage	$I_{OL} = 12\text{ mA}$			0.8	V
V_{OH}	Output High Voltage	$I_{OH} = -12\text{ mA}$	2.1			V
I_{IL}	Input Low Current	$V_{IN} = 0\text{V}$			50	μA
I_{IH}	Input High Current	$V_{IN} = V_{DD}$			50	μA

AC Electrical Characteristics: $T_A = 0^{\circ}\text{C}$ to 70°C , $V_{DD} = 3.3\text{V} \pm 10\%$

Parameter	Description	Test Condition	Min	Typ	Max	Unit
f_{OUT}	Output Frequency	30-pF load ^[5]	25		140	MHz
t_R	Output Rise Time	0.8V to 2.0V, 30-pF load			2.1	ns
t_F	Output Fall Time	2.0V to 0.8V, 30-pF load			2.5	ns
t_{CLKR}	Input Clock Rise Time ^[2]				4.5	ns
t_{CLKF}	Input Clock Fall Time ^[2]				4.5	ns
t_{PEJ}	CLK to FBIN Skew Variation ^[3, 4]	Measured at $V_{DD}/2$	-350	0	350	ps
t_{SK}	Output to Output Skew	All outputs loaded equally	-100	0	100	ps
t_D	Duty Cycle	30-pF load	43	50	58	%
t_{LOCK}	PLL Lock Time	Power supply stable			1.0	ms
t_{JC}	Jitter, Cycle-to-Cycle ^[5]				150	ps

Notes

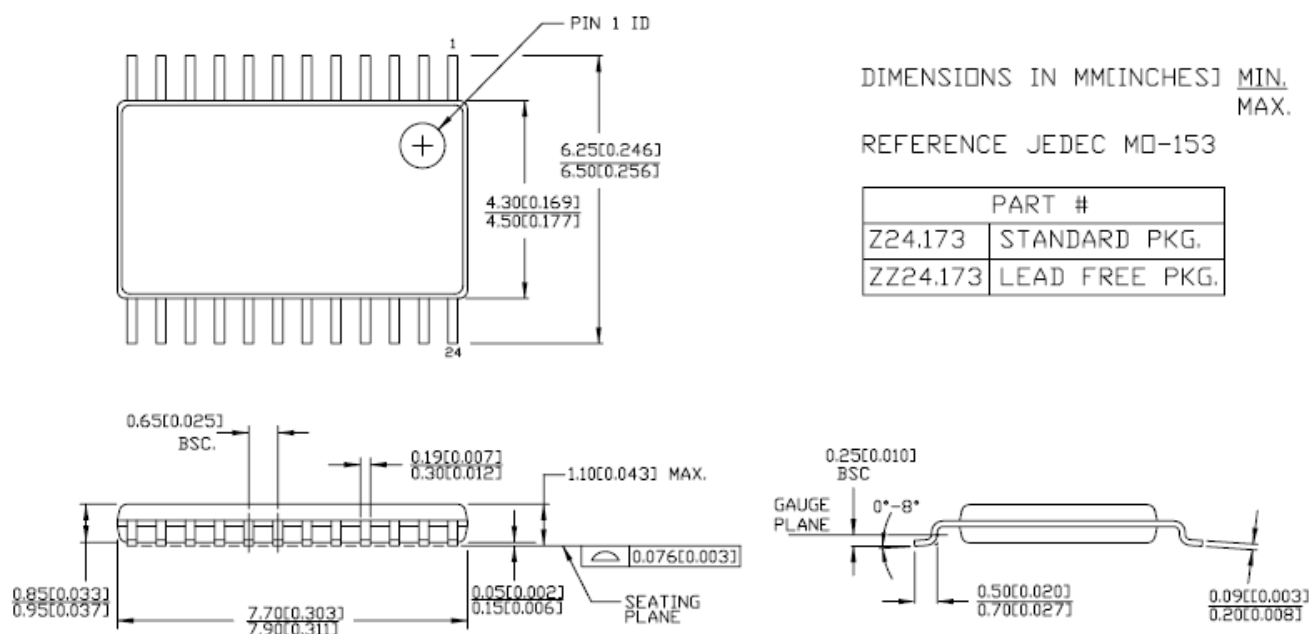
1. Multiple Supplies: The voltage on any input or IO pin cannot exceed the power pin during power up. Power supply sequencing is NOT required.
2. Longer input rise and fall time degrades skew and jitter performance.
3. Skew is measured at $V_{DD}/2$ on rising edges.
4. Duty cycle is measured at $V_{DD}/2$.
5. Production tests are run at 133 MHz.
6. For frequencies below 40 MHz, Cycle-to-Cycle Jitter degrades to 175 ps.

Ordering Information

Ordering Code	Status	Package Type
W232-09X	Obsolete	24-pin TSSOP
W232-09XT	Obsolete	24-pin TSSOP, Tape & Reel
W232-10X	Active	24-pin TSSOP
W232-10XT	Active	24-pin TSSOP, Tape & Reel
Pb-Free		
W232ZXC-10	Active	24-pin TSSOP
W232ZXC-10T	Active	24-pin TSSOP, Tape & Reel

Package Diagram

Figure 5. 24-Pin Thin Shrink Small Outline Package (TSSOP)



51-85119-A

Document History Page

Document Title: W232 Ten Output Zero Delay Buffer Document Number: 38-07167				
REV.	ECN NO.	Submission Date	Orig. of Change	Description of Change
**	110277	10/25/01	SZV	Change from Spec number: 38-00827 to 38-07167
*A	111278	03/22/02	IKA	Put package type in order information table for TSSOP
*B	122808	12/15/02	RBI	Add Power up Requirements to Operating Conditions Information
*C	2548211	08/15/08	LJN	Obsolete spec
*D	2635369	01/21/09	KVM	Updated template Un-obsolete spec Indicate W232-09 is obsolete in Ordering Information table
*E	2699171	04/28/2009	KVM/PYRS	Added Ordering Information Table

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